

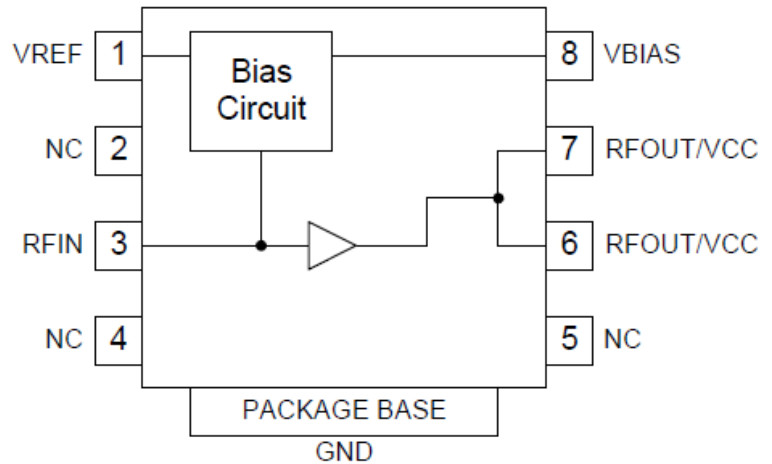


Features

- High Linearity: OIP3=46dBm at 880MHz
- Low Noise: NF<4dB
- Low DC Power: 5V, 90mA
- 400MHz to 2700MHz Operation
- Thermally Enhanced Slug Package

Applications

- GaAs Pre-Driver for Base Station Amplifiers
- PA Stage for Commercial Wireless Infrastructure
- Class AB Operation for DCS, PCS, UMTS, and WLAN Transceiver Applications
- 2nd/3rd Stage LNA for Wireless Infrastructure



Functional Block Diagram

Product Description

The RFPA3807 is a GaAs HBT linear power amplifier specifically designed for Wireless Infrastructure applications. Using a highly reliable GaAs HBT fabrication process, this high performance single-stage amplifier achieves ultra-high linearity over a broad frequency range. It also offers low noise figure making it an excellent solution for 2nd and 3rd stage LNAs. The RFPA3807 also exhibits excellent thermal performance through the use of a thermally-enhanced plastic surface-mount slug package.

Ordering Information

| | |
|-----------------|---|
| RFPA3807SQ | Sample Bag with 25 pieces |
| RFPA3807SR | 7" Reel with 100 pieces |
| RFPA3807TR7 | 7" Reel with 750 pieces |
| RFPA3807TR13 | 13" Reel with 2500 pieces |
| RFPA3807PCK-410 | 869MHz to 960MHz PCBA with 5-piece Sample Bag |
| RFPA3807PCK-411 | 2110MHz to 2170MHz PCBA with 5-piece Sample Bag |

Optimum Technology Matching® Applied

- | | | | |
|--|--------------------------------------|-------------------------------------|------------------------------------|
| <input checked="" type="checkbox"/> GaAs HBT | <input type="checkbox"/> SiGe BiCMOS | <input type="checkbox"/> GaAs pHEMT | <input type="checkbox"/> GaN HEMT |
| <input type="checkbox"/> GaAs MESFET | <input type="checkbox"/> Si BiCMOS | <input type="checkbox"/> Si CMOS | <input type="checkbox"/> BiFET HBT |
| <input type="checkbox"/> InGaP HBT | <input type="checkbox"/> SiGe HBT | <input type="checkbox"/> Si BJT | <input type="checkbox"/> LDMOS |

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Absolute Maximum Ratings

| Parameter | Rating | Unit |
|--|-------------|------|
| Supply Voltage (V_{CC} and V_{BIAS}) | 6.5 | V |
| Reference Current (I_{REF}) | 5 | mA |
| DC Supply Current (I_C) | 256 | mA |
| CW Input Power, 2:1 Output VSWR | 23 | dBm |
| Output Load VSWR at P3dB | 5:1 | |
| Operating Junction Temperature | 160 | °C |
| Operating Temperature Range (T_L) | -40 to +85 | °C |
| Storage Temperature | -55 to +150 | °C |
| ESD Rating: Human Body Model | Class 1B | |
| Moisture Sensitivity Level | MSL 2 | |

- Notes: 1. The maximum ratings must all be met simultaneously.
 2. $P_{diss} = P_{DC} + P_{RFIN} - P_{RFOUT}$
 3. $T_J = T_L + P_{diss} * R_{th}$



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

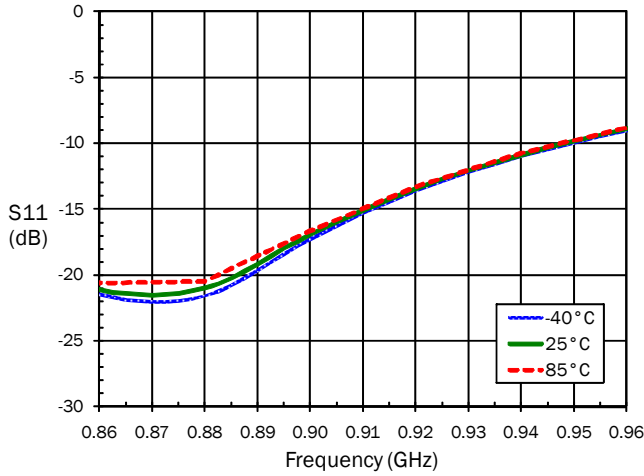
RoHS status based on EUDirective2002/95/EC (at time of this document revision).

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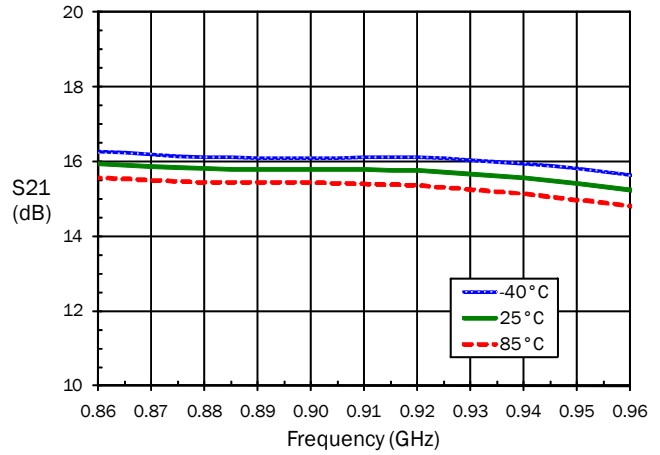
| Parameter | Specification | | | Unit | Condition |
|---------------------------------|---------------|------|------|------|--|
| | Min. | Typ. | Max. | | |
| 860MHz to 960MHz | | | | | |
| Frequency | 860 | | 960 | MHz | $V_{CC}=5.0V, V_{BIAS}=5.0V, I_{CQ}=90mA$ Tuned for 880MHz useful to 960MHz |
| Input Power (P_{IN}) | | | 15 | dBm | $V_{CC}<6.0V$, max recommended |
| Gain (S21) | | 15.8 | | dB | |
| OIP3 | | 43 | | dBm | 12dBm/tone, tone spacing=1MHz |
| P1dB | | 25 | | dBm | |
| Efficiency at P3dB | | 58 | | % | At P3dB |
| Input Return Loss (S11) | | 18 | | dB | 869MHz to 894MHz band |
| Output Return Loss (S22) | | 11 | | dB | |
| Noise Figure | | 3.5 | | dB | 869MHz to 894MHz band |
| WCDMA Ch Power at -65dBc ACPR | | 12.9 | | dBm | 3GPP 3.5, Test Model 1, 64 DPCH |
| WCDMA Ch Power at -55dBc ACPR | | 14.6 | | dBm | 3GPP 3.5, Test Model 1, 64 DPCH |
| UMTS2100 | | | | | |
| Frequency | 2110 | 2140 | 2170 | MHz | $V_{CC}=5.0V, V_{BIAS}=5.0V, I_{CQ}=90mA$ |
| Input Power (P_{IN}) | | | 15 | dBm | $V_{CC}<6.0V$, max recommended |
| Gain (S21) | | 13.7 | | dB | |
| OIP3 | | 42 | | dBm | 12dBm/tone, tone spacing=1MHz |
| P1dB | | 24 | | dBm | |
| Efficiency at P3dB | | 56 | | % | At P3dB |
| Input Return Loss (S11) | | 15 | | dB | |
| Output Return Loss (S22) | | 13.5 | | dB | |
| Noise Figure | | 2.9 | | dB | |
| WCDMA Ch Power at -65dBc ACPR | | 11.5 | | dBm | 3GPP 3.5, Test Model 1, 64 DPCH |
| WCDMA Ch Power at -55dBc ACPR | | 13.2 | | dBm | 3GPP 3.5, Test Model 1, 64 DPCH |
| Power Supply | | | | | |
| Operating Current (Quiescent) | 80 | 90 | 115 | mA | At $V_{CC}=5.0V$ |
| Operating Voltage (V_{CC}) | | 5.0 | 6.0 | V | Max recommended collector voltage |
| Thermal Resistance (R_{TH}) | | 95 | | C/W | At quiescent current, no RF |
| Power Down Current | | | 20 | µA | At $V_{REF}=0V$ |

Typical Performance
(869 MHz to 960 MHz Application Circuit)

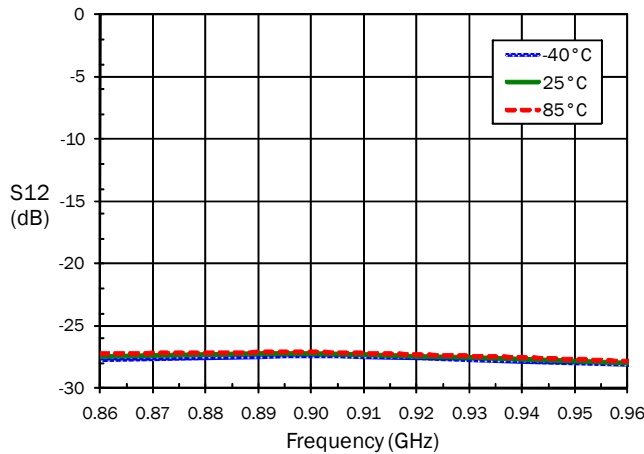
S11 versus Frequency



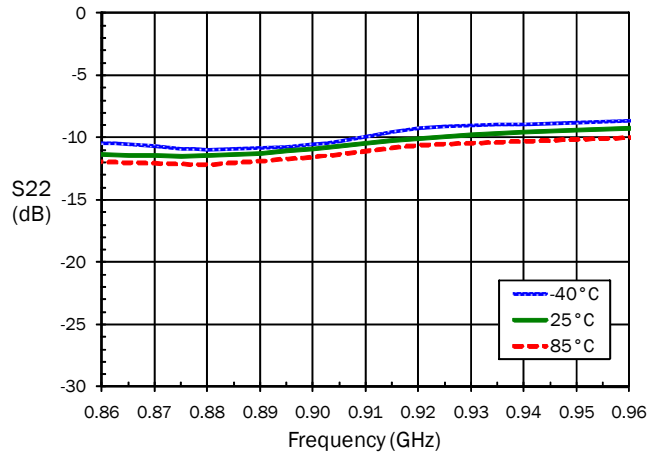
S21 versus Frequency



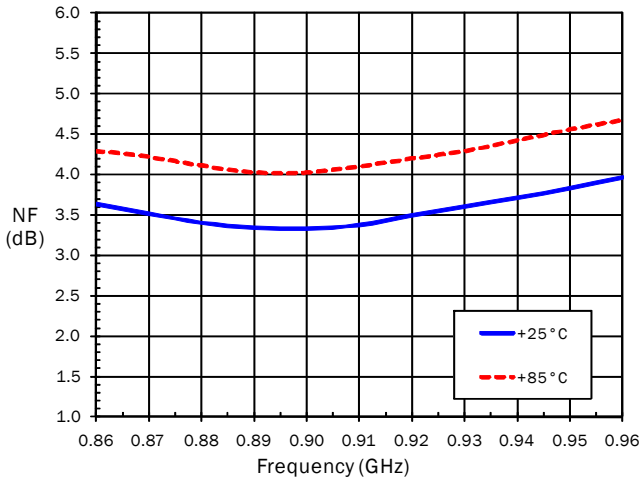
S12 versus Frequency



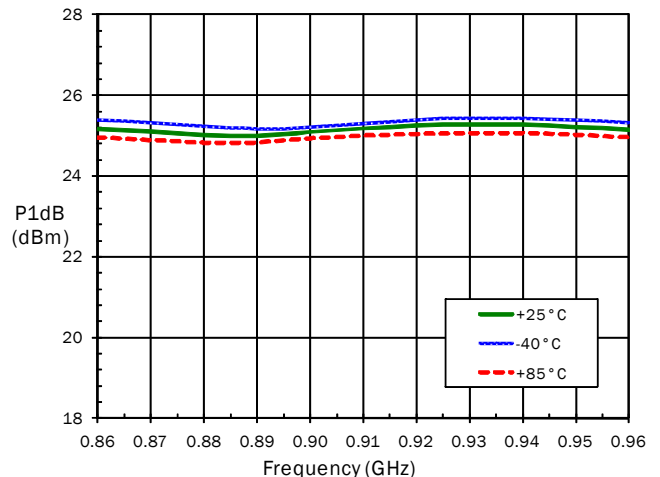
S22 versus Frequency



Noise Figure versus Frequency

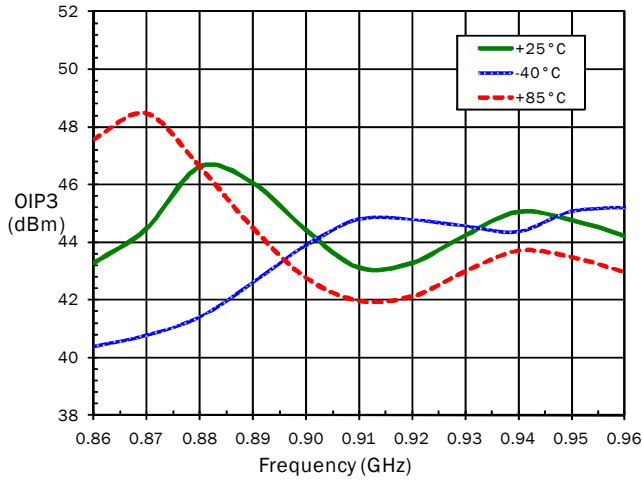


P1dB versus Frequency

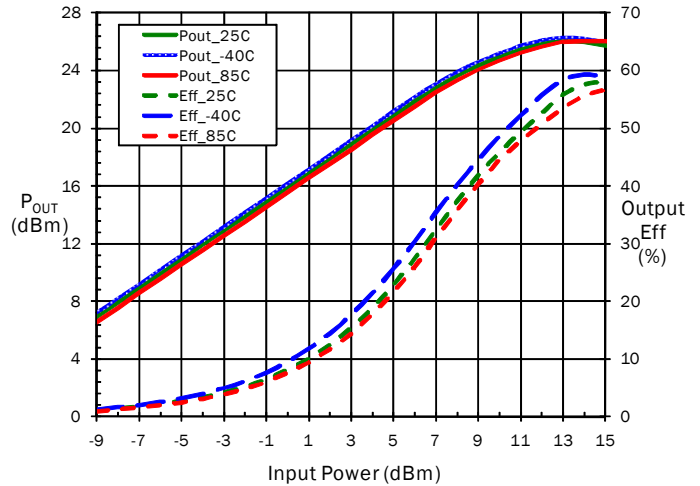


Typical Performance (869 MHz to 960 MHz Application Circuit)

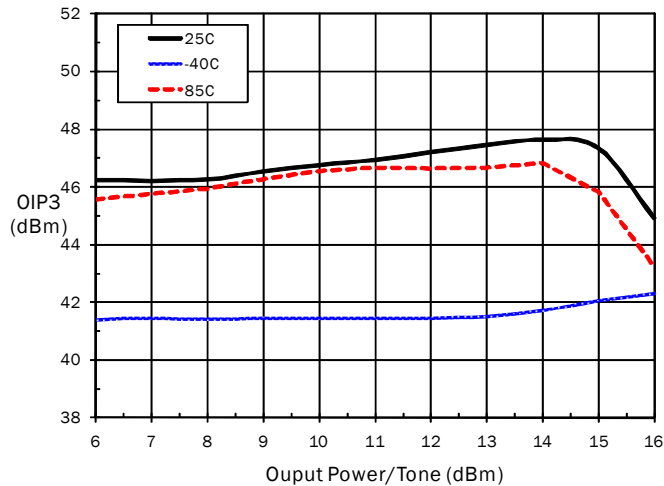
OIP3 vs Freq. (12dBm tones, 1 MHz spacing)



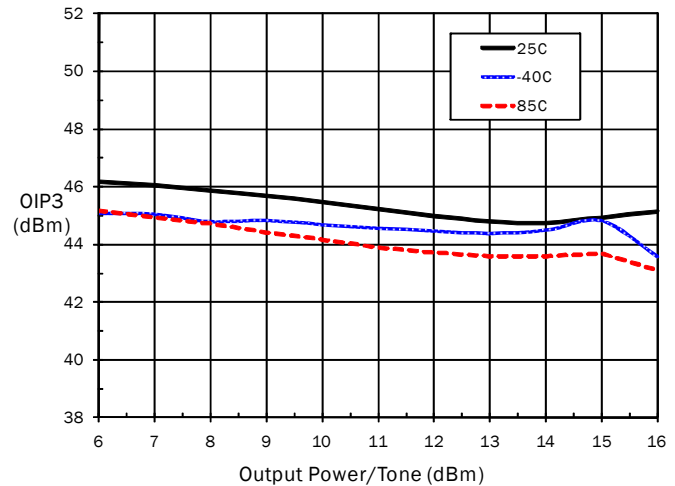
P_{OUT} versus P_{IN} at 880MHz



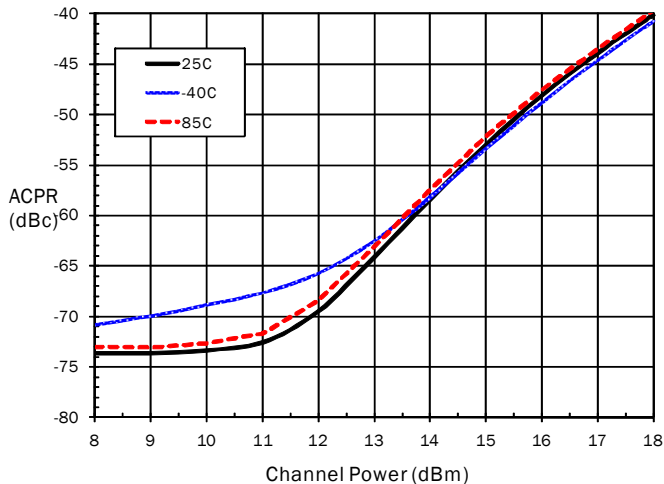
OIP3 versus Tone Power (880MHz, 1MHz Spacing)



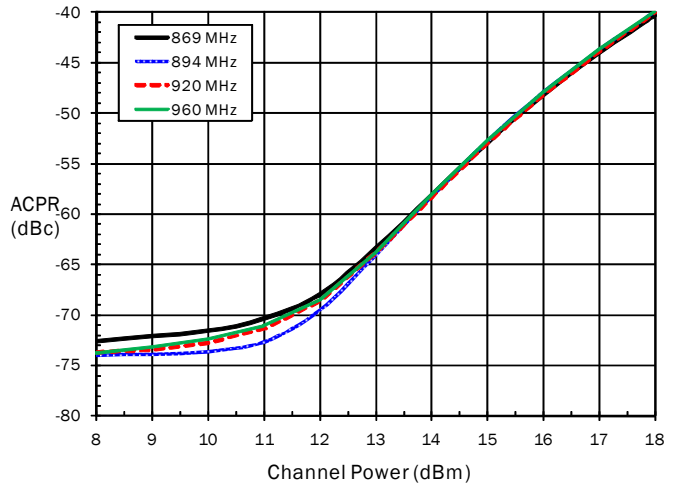
OIP3 versus Tone Power (940MHz, 1MHz Spacing)



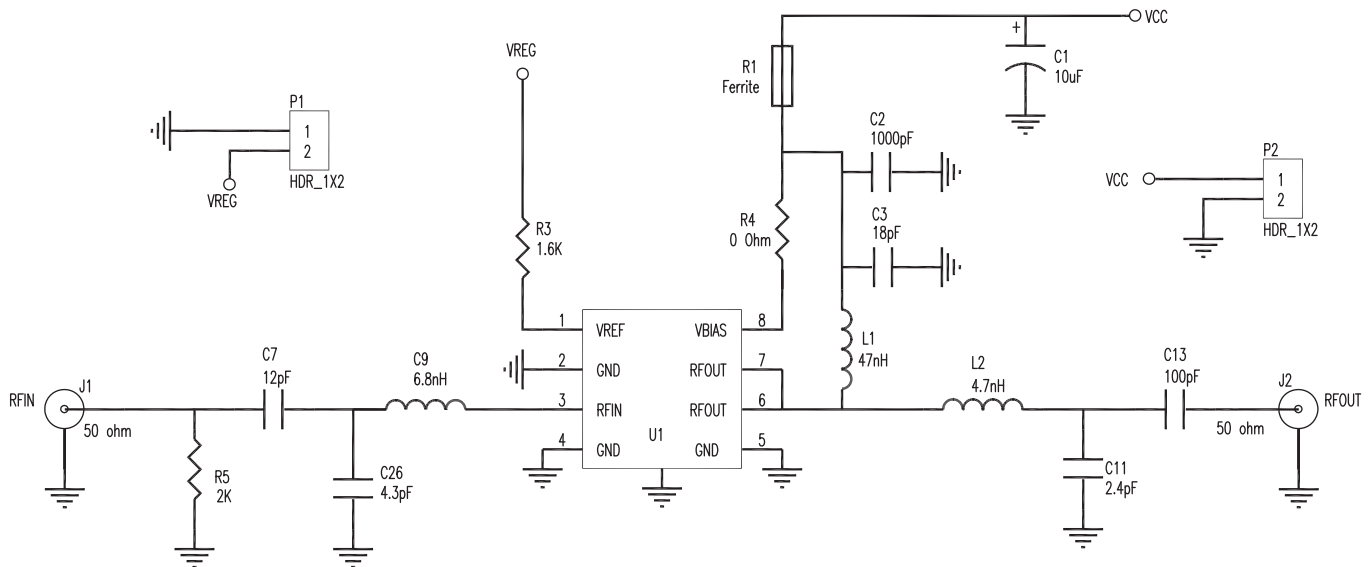
ACPR versus WCDMA Channel Power (880MHz)



ACPR versus WCDMA Channel Power (25 °C)



Evaluation Board Schematic (869MHz to 960MHz Application Circuit)



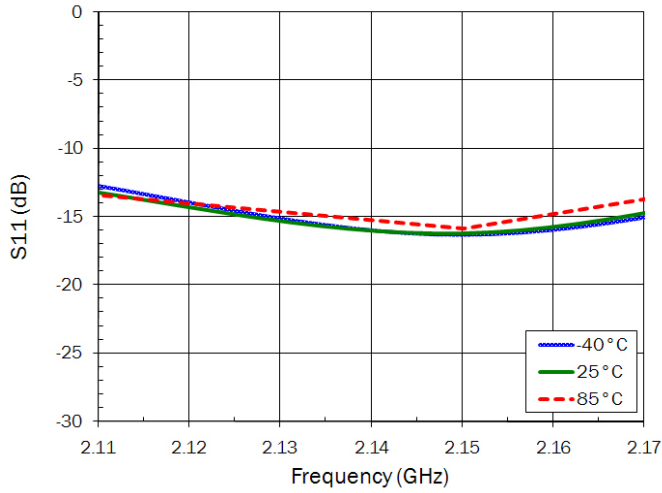
EVB BOM

(869MHz to 960MHz Application Circuit)

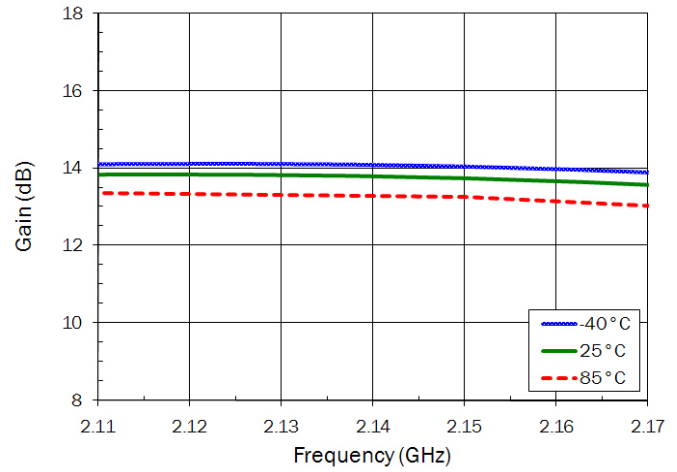
| Description | Reference Designator | Manufacturer | Manufacturer's P/N |
|-------------------------------------|---|---------------------|---------------------|
| PCB, PA380X410 | | DDI | PA380X410(A) |
| RFPA3807SB | U1 | RFMD | RFPA3807SB |
| CAP, 10µF, 10%, 10V, TANT-A | C1 | AVX Corporation | TAJA106K010R |
| CAP, 1000pF, 10%, 50V, X7R, 0402 | C2 | Taiyo Yuden | RM UMK105BJ102KV-F |
| CAP, 18pF, 5%, 50V, COG, 0402 | C3 | Taiyo Yuden | RM UMK105 CG180JV-F |
| CAP, 12pF, 5%, 50V, COG, 0402 | C7 | Murata | GRM1555C1H120JZ01E |
| CAP, 4.3pF, ±0.25pF, 50V, COG, 0402 | C26 | Taiyo Yuden | RM UMK105CG4R3C |
| IND, 6.8nH, 5%, M/L, 0402 | C9 | Toko | LL1005-FHL6N8J |
| CAP, 2.4pF, ±0.25pF, 50V, COG, 0402 | C11 | Taiyo Yuden | RM UMK105CG2R4CW |
| CAP, 100pF, 5%, 50V, COG, 0402 | C13 | Murata | GRM1555C1H101JZ01D |
| IND, 47nH, 5%, W/W, 0603 | L1 | Coilcraft | 0603HC-47NXJLW |
| IND, 4.7nH, ±0.3nH, M/L, 0402 | L2 | Toko | LL1005-FH4N7S |
| CONN, SMA, END, LNCH, FLT, 0.068" | J1, J2 | Emerson | 142-0701-851 |
| CONN, HDR, ST, 2-PIN, 0.100" | P1, P2 | Sullins Electronics | PBC02SAAN |
| FERRITE BEAD, 260Ω, 2A, 0603 | R1 | Murata | BLM18EG221SN1D |
| RES, 1.6K, 5%, 1/16W, 0402 | R3 | Kamaya, Inc | RMC1/16S-162JTH |
| RES, 0Ω, 0603 | R4 | Kamaya, Inc | RMC1/16JPTP |
| RES, 2K, 5%, 1/16W, 0402 | R5 | Kamaya, Inc | RMC1/16S-202JTH |
| Do Not Place (DNP) | C4-C6, C8 C10, C12, C14-C25, C27-C29, R2, R6-R8 | | |

Typical Performance (2110MHz to 2170MHz Application Circuit)

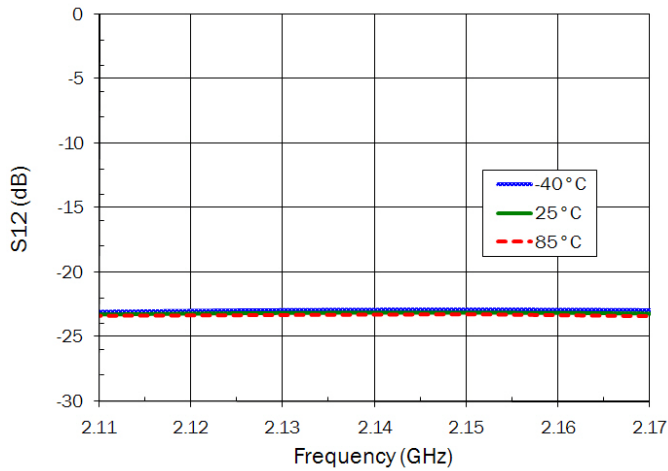
S11 versus Frequency



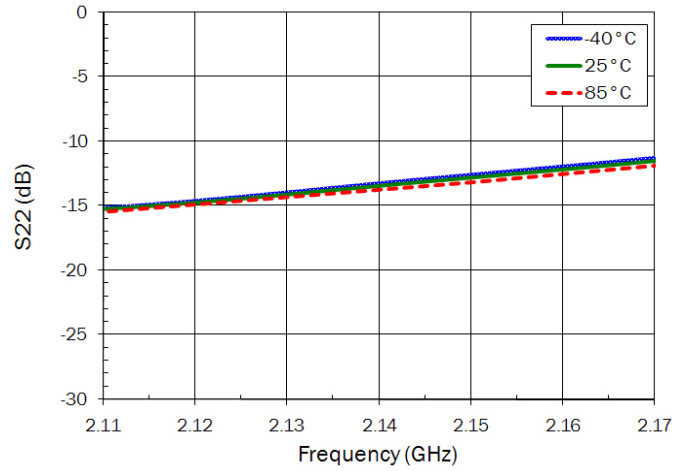
S21 versus Frequency



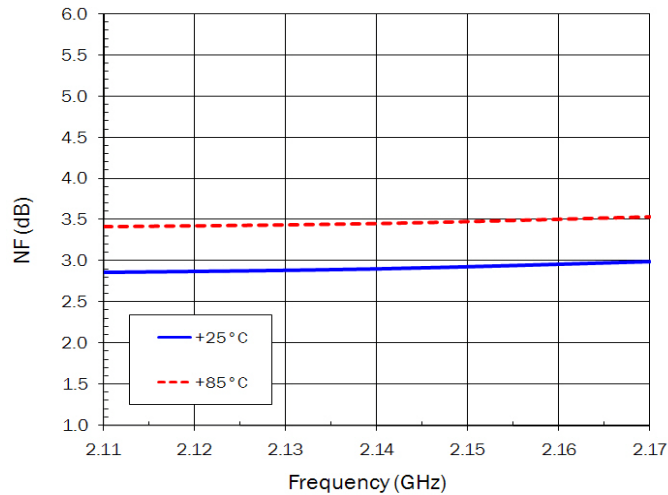
S12 versus Frequency



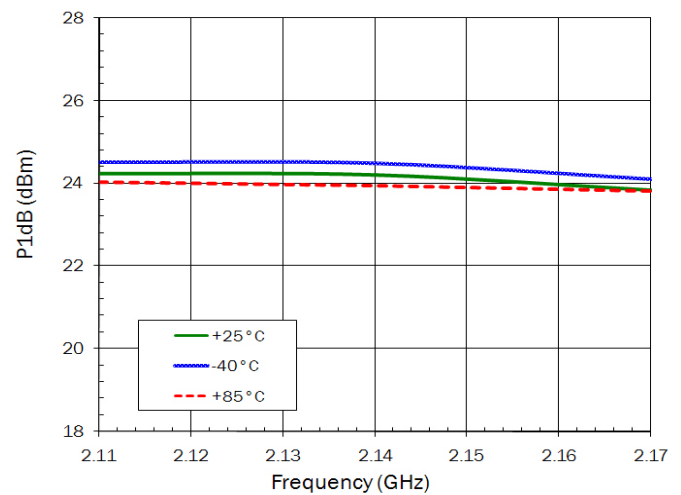
S22 versus Frequency



Noise Figure versus Frequency

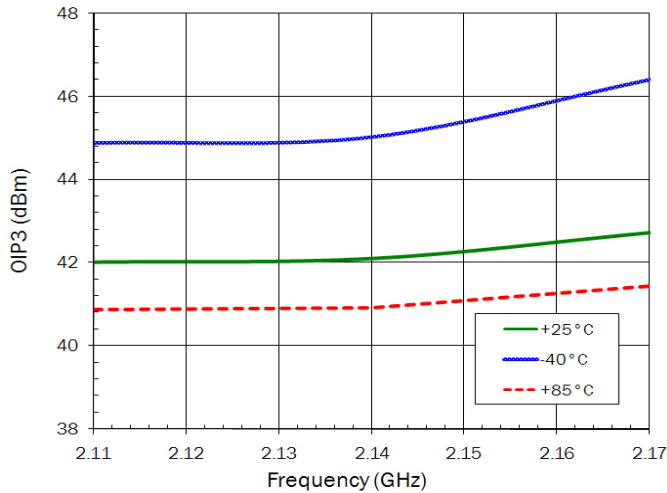


P1dB versus Frequency

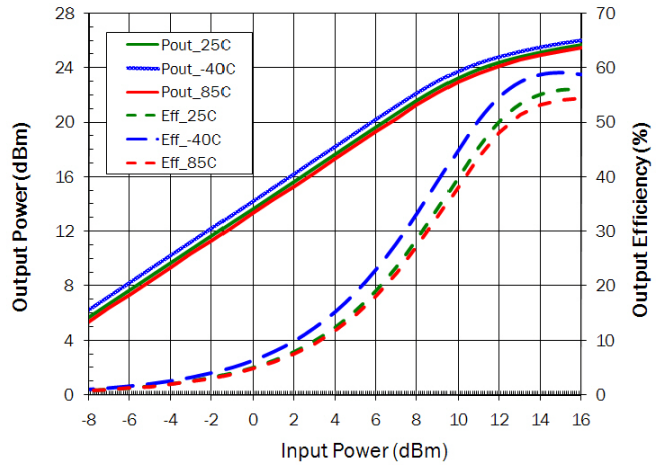


Typical Performance
(2110MHz to 2170MHz Application Circuit)

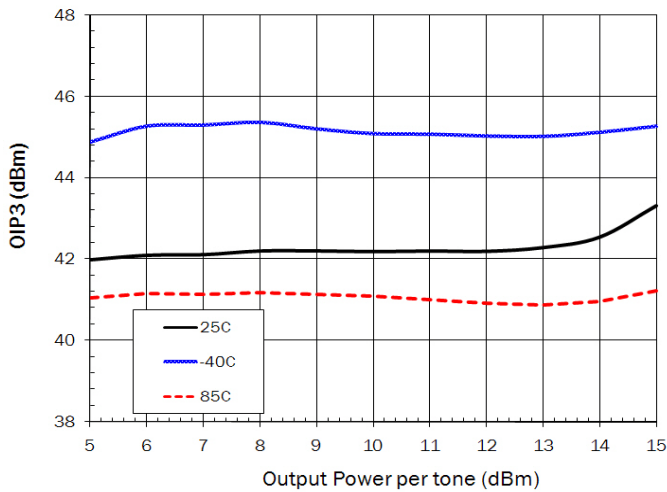
OIP3 vs Freq. (12dBm tones, 1 MHz spacing)



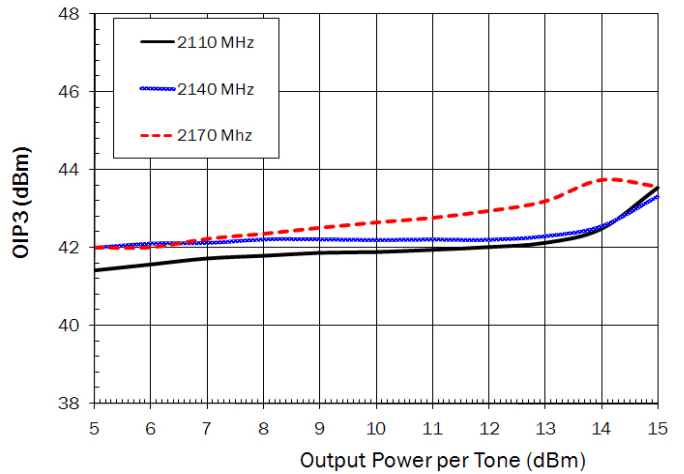
Pout versus Pin @2140MHz



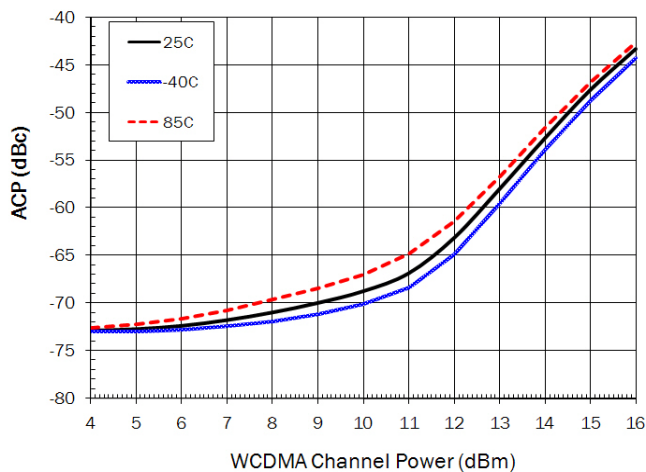
OIP3 vs Tone Power (2140MHz, 1 MHz spacing)



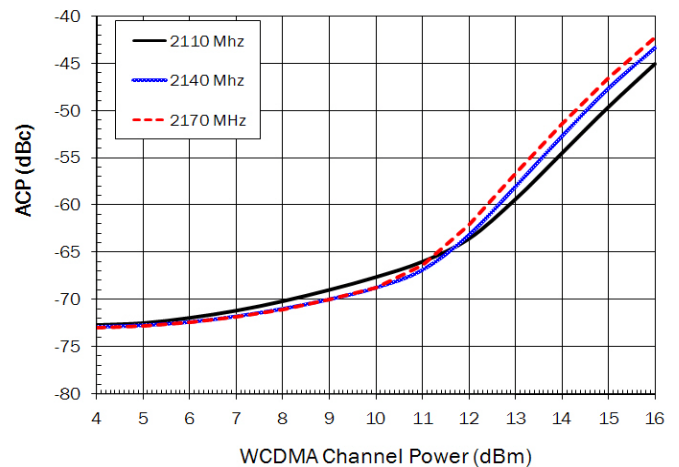
OIP3 vs Tone Power (1 MHz Spacing, 25 ° C)



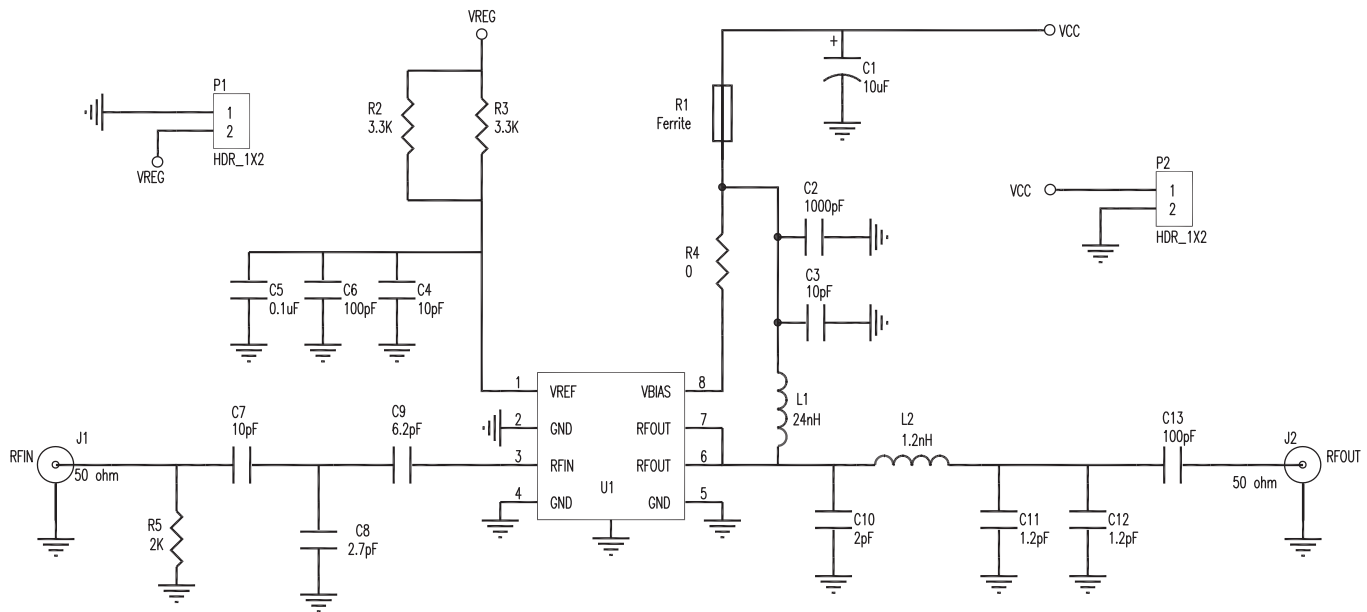
ACP versus WCDMA Channel Power (2140MHz)



ACP versus Channel Power (25 ° C)



Evaluation Board Schematic (2110MHz to 2170MHz Application Circuit)

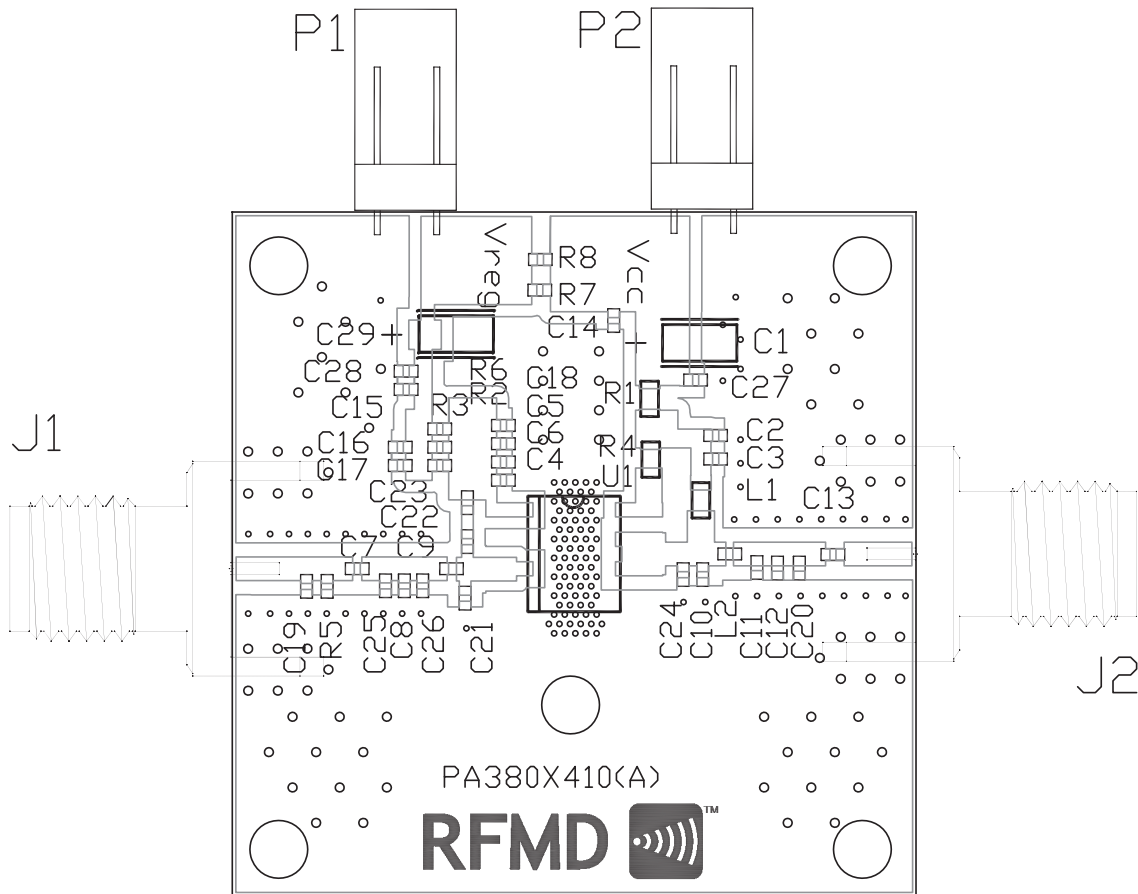


EVB BOM

(2110MHz to 2170MHz Application Circuit)

| Description | Reference Designator | Manufacturer | Manufacturer's P/N |
|--|--|-------------------------|--------------------|
| PCB, PA380X410 | | | PA380X410(A) |
| CAP, 10 μ F, 10%, 10V, TANT-A | C1 | AVX Corporation | TAJA106K010R |
| CAP, 1000pF, 10%, 50V, X7R, 0402 | C2 | Taiyo Yuden (USA), Inc. | RM UMK105BJ102KV-F |
| CAP, 10pF, 5%, 50V, COG, 0402 | C3, C4, C7 | Murata Electronics | GRM1555C1H100JZ01E |
| CAP, 0.1 μ F, 10%, 16V, X7R, 0402 | C5 | Murata Electronics | GRM155R71C104KA88D |
| CAP, 100pF, 5%, 50V, COG, 0402 | C6 | Taiyo Yuden (USA), Inc. | RM UMK105CG101JV-F |
| CAP, 2.7pF, \pm 0.1pF, 50V, COG, 0402 | C8 | Murata Electronics | GRM1555C1H2R7BZ01E |
| CAP, 6.2pF, \pm 0.1pF, 50V, COG, 0402 | C9 | Murata Electronics | GRM1555C1H6R2BZ01E |
| CAP, 2pF, \pm 0.1pF, 50V, HI-Q, 0402 | C10 | Johanson Technology | 500R07S2R0BV4TD |
| CAP, 1.2pF, \pm 0.1pF, 50V, HI-Q, 0402 | C11, C12 | Johanson Technology | 500R07S1R2BV4TD |
| CAP, 100pF, 5%, 50V, COG, 0402 | C13 | Murata Electronics | GRM1555C1H101JZ01D |
| IND, 24nH, 5%, W/W, 0603 | L1 | Coilcraft | 0603HC-24NXJLW |
| IND, 1.2nH, \pm 0.3nH, M/L, 0402 | L2 | Toko America, Inc. | LL1005-FH1N2S |
| CONN, SMA, END, LAUNCH, RND, PIN, 0.062" | J1, J2 | GIGALANE CO., LTD. | PAF-S05-008 |
| CONN, HDR, ST, 2-PIN, 0.100 | P1, P2 | Sullins Electronics | PBC02SAAN |
| RFPA3807SB | U1 | RFMD | RFPA3807SB |
| FER, BEAD, 260 Ω , 2A, 0603 | R1 | Murata Electronics | BLM18EG221SN1D |
| RES, 3.3K, 5%, 1/16W, 0402 | R2, R3 | Kamaya, Inc | RMC1/16S-332JTH |
| RES, 0 Ω , 0603 | R4 | Kamaya, Inc | RMC1/16JPTP |
| RES, 2K, 5%, 1/16W, 0402 | R5 | Kamaya, Inc | RMC1/16S-202JTH |
| Do Not Place | C14, C15, C16, C17, C18, C19, C20, C21, C22, C23, C24, C25, C26, C27, C28, C29, R6, R7, R8 | | |

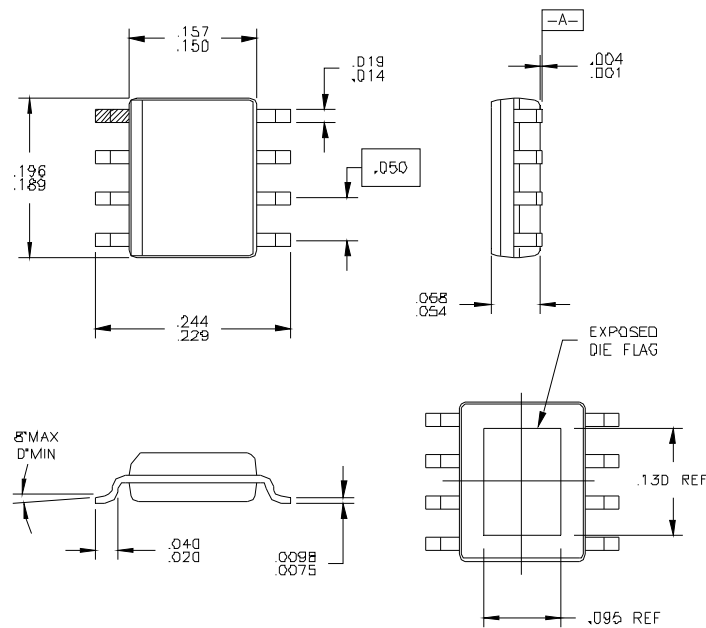
Evaluation Board Assembly Drawing



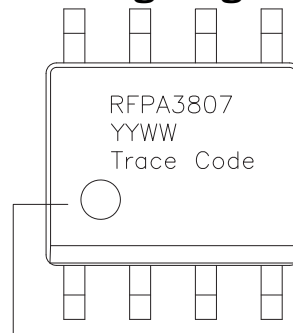
| Pin | Function | Description |
|------|------------|---|
| 1 | VREF | Control input to the active bias circuit to set I_{CQ} . Can be used as a power-down pin. |
| 2 | NC | No connection. |
| 3 | RF IN | RF input. External DC block is required. |
| 4 | NC | No connection. |
| 5 | NC | No connection. |
| 6 | RF OUT/VCC | RF output, device collector. |
| 7 | RF OUT/VCC | RF output, device collector. |
| 8 | VBIAS | Supply voltage for the active bias circuit. |
| EPAD | GND | DC and RF ground. Must be soldered to EVB ground plane over a bed of vias for thermal and RF performance. |

Package Drawing

Dimensions in inches (millimeters)



Branding Diagram



Pin 1 Indicator

YYWW=date code where YY=year, WW=week. Trace Code=lot code assigned by packaging supplier.